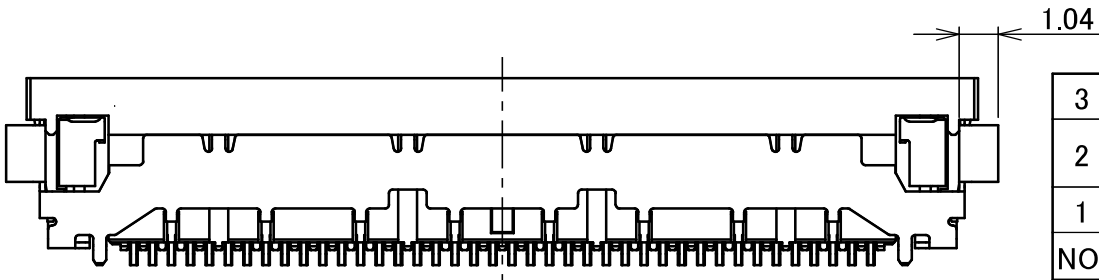
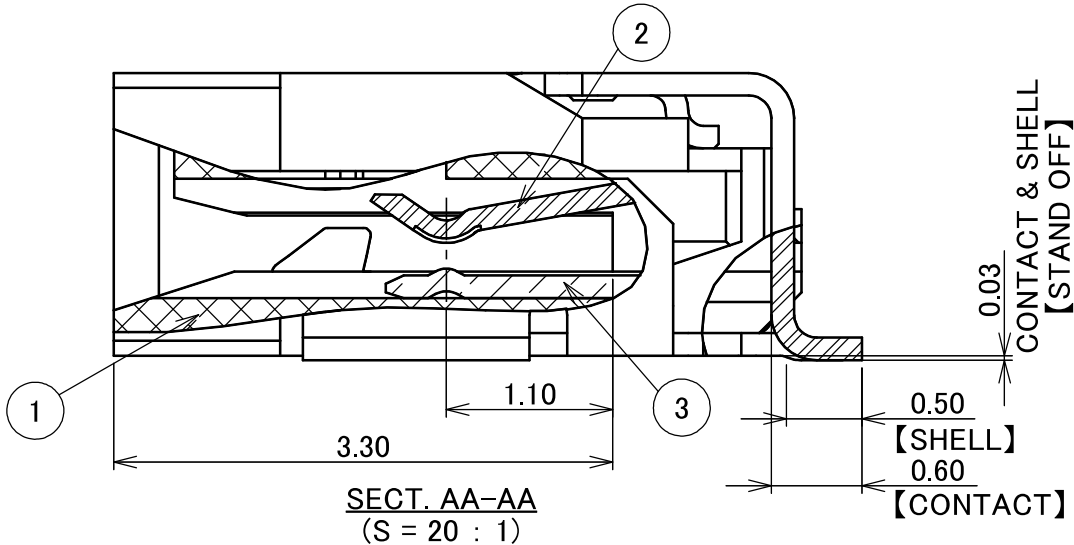
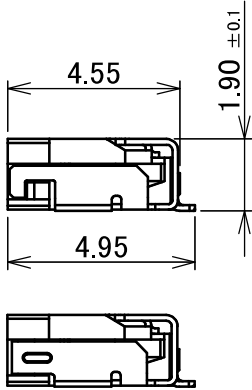
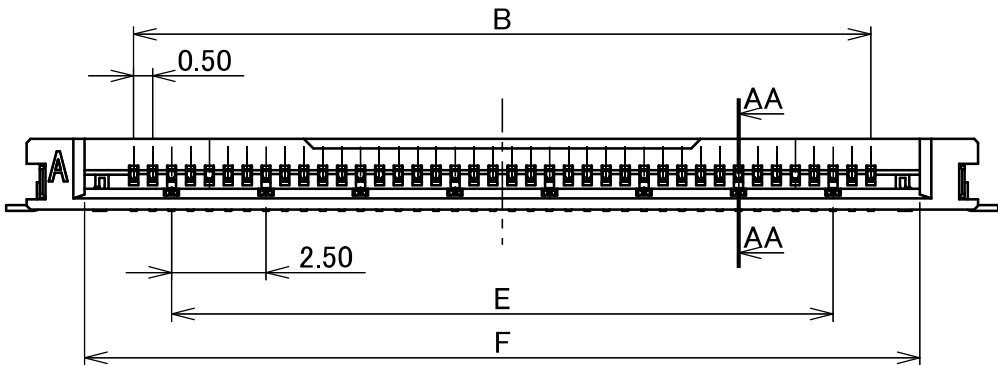
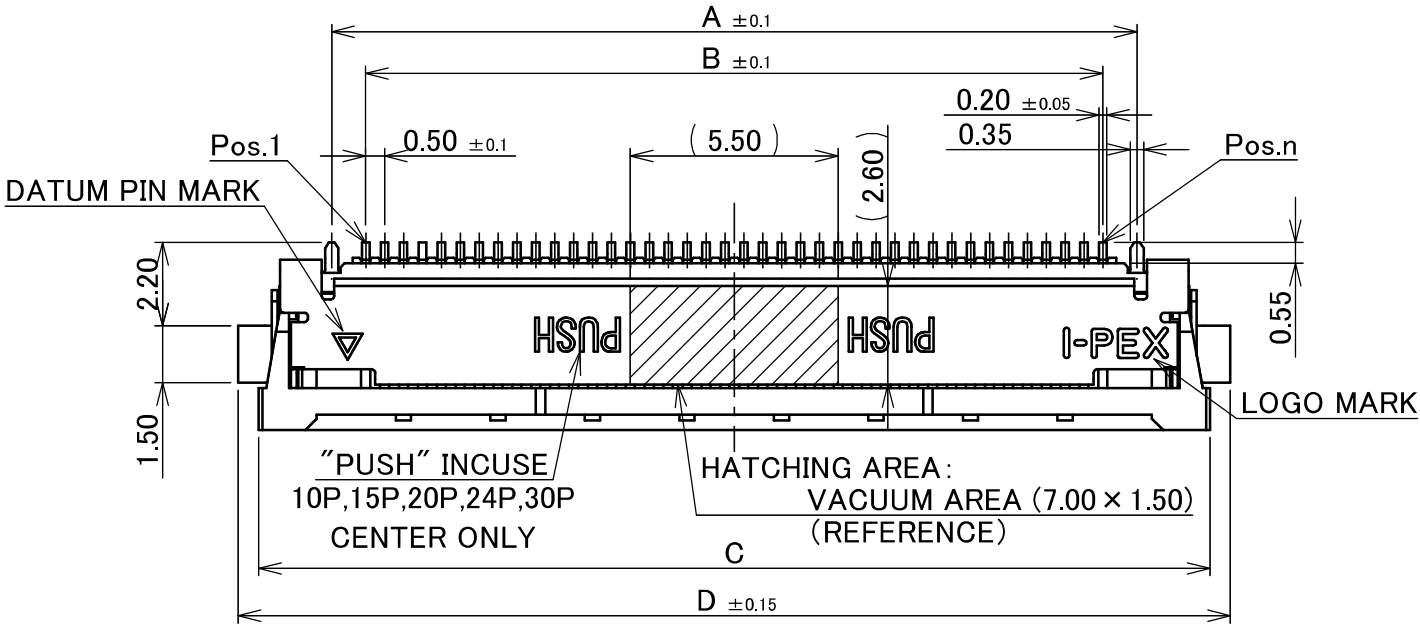
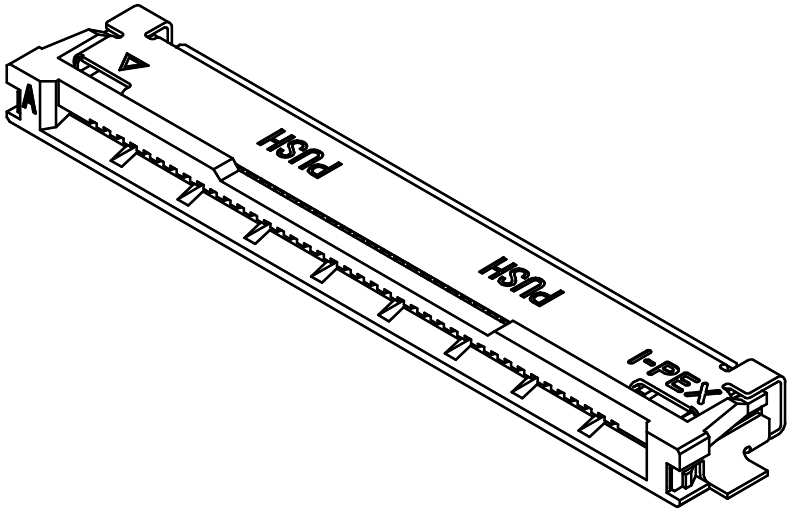
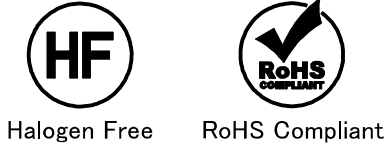


Recommended P/N		20535-0**E-02-P					
PART No.	POS.	A	B	C	D	E	F
20535-010E-02-*	10P	6.30	4.50	10.17	11.25	2.50	7.10
20535-015E-02-*	15P	8.80	7.00	12.67	13.75	5.00	9.60
20535-020E-02-*	20P	11.30	9.50	15.17	16.25	7.50	12.10
20535-024E-02-*	24P	13.30	11.50	17.17	18.25	7.50	14.10
20535-030E-02-*	30P	16.30	14.50	20.17	21.25	12.50	17.10
20535-040E-02-*	40P	21.30	19.50	25.17	26.25	17.50	22.10

P/N: 20535-0**E-02-*

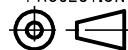
NOTHING: ORIGINAL
P : PFAS FREE
Pos.



3	SHELL	PHOSPHOR BRONZE	Sn 1.00 μ m MIN. OVER Ni 1.00 μ m MIN. PLATING
2	CONTACT	PHOSPHOR BRONZE	Au OVER Ni PLATING CONTACT AREA: Au 0.03 μ m MIN. OVER Ni 1.00 μ m MIN.
1	HOUSING	LCP	UL94V-0, BLACK
NO.	DISCRIPTION	MATERIAL	FINISH , REMARKS

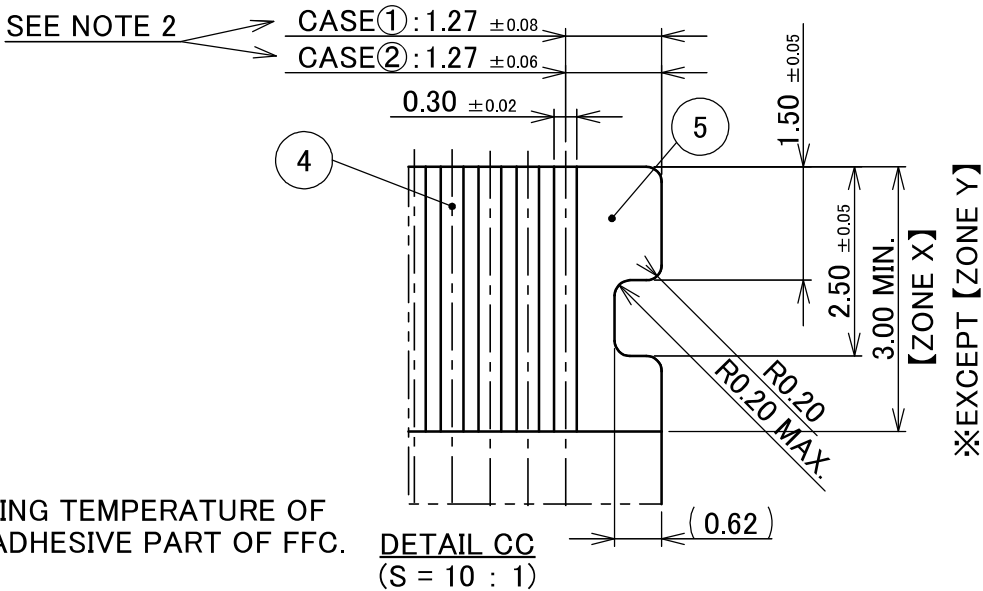
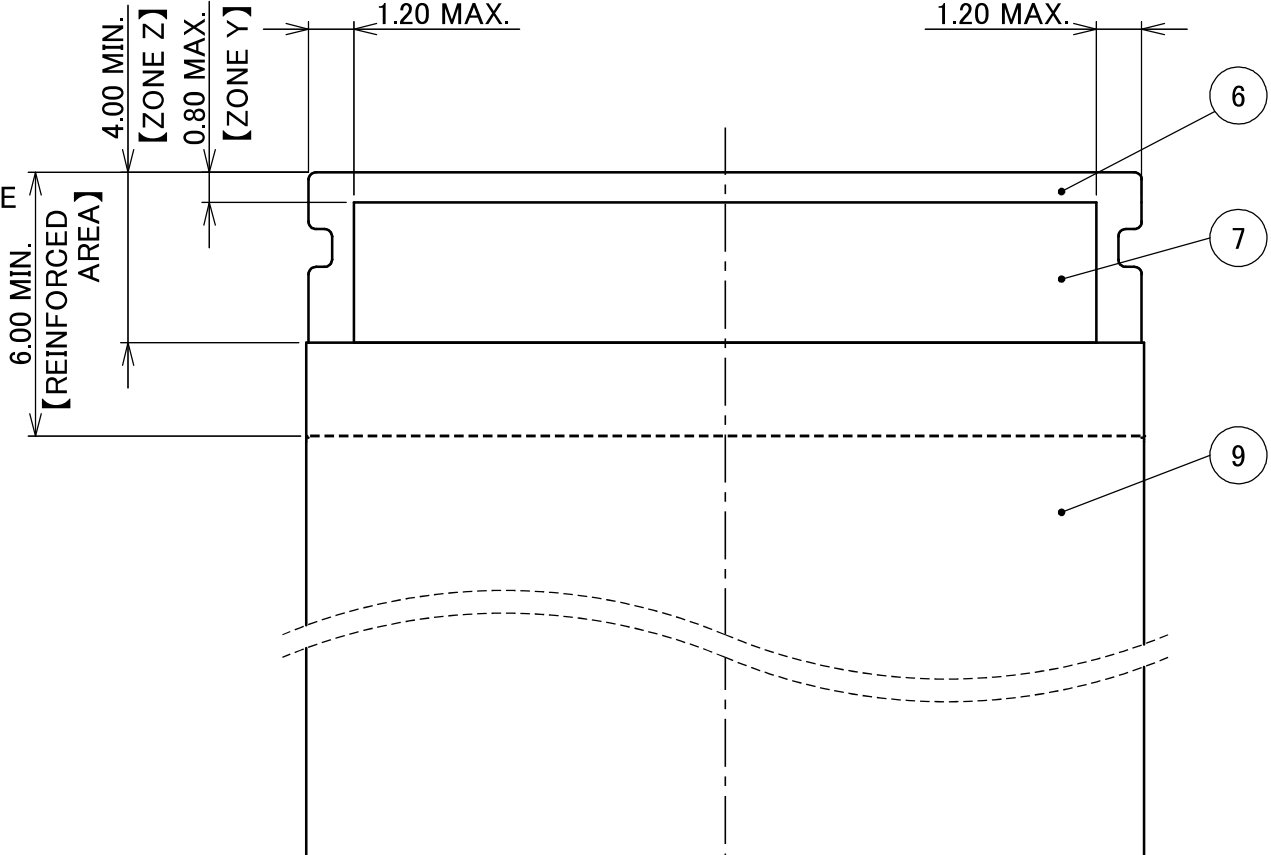
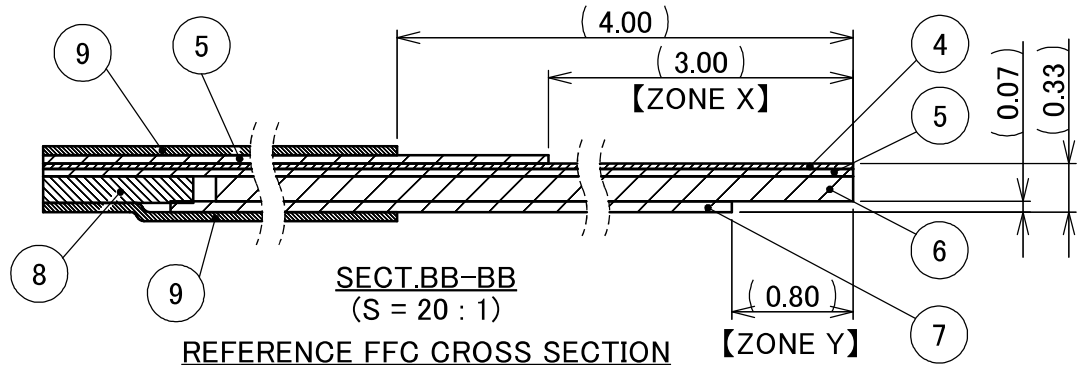
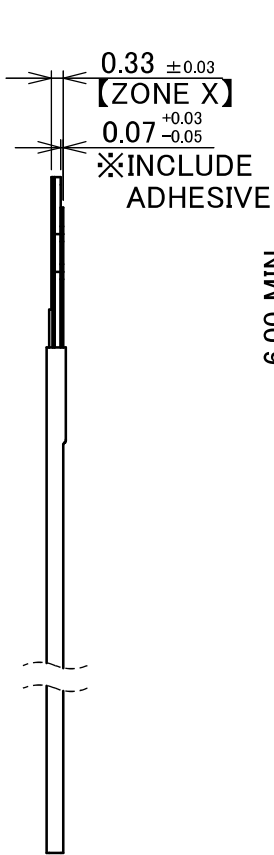
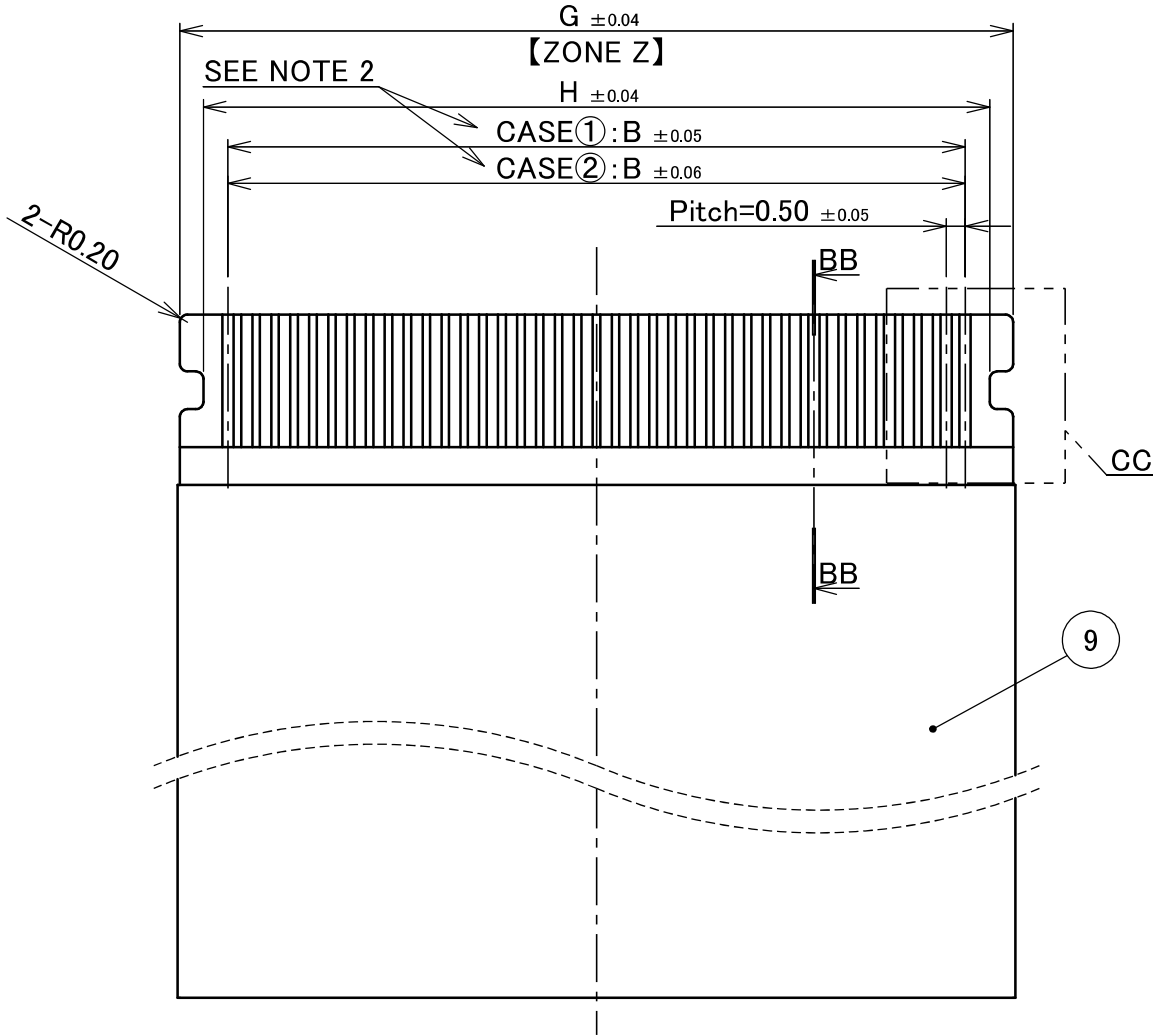
15	ZC00180	Mino	Oct./17/'25	T.M	ANGLE	±2°	6 OVER 30 MAX.	±0.3		PROJECTION	SERIES No.	CUSTOMER COPY		
14	Z230333	K.W	Mar./23/'23	M.T	6 MAX.	±0.2	30 OVER 120 MAX.	±0.5			R6			
13	Z220271	K.H	Mar./10/'22	H.I	GENERAL TOLERANCE.				TITLE EVAFLEX® 5-VS			SCALE	I-PEX	
12	Z211485	K.H	Nov./30/'21	H.I	DWG.	DATE						5:1		
11	Z201214	H.K	Nov./26/'20	Y.S	CHK.	2012/04/16						UNIT		
10	Z180880	T.T	July/05/'18	Y.S	J.Tateishi			mm						
REV.	ECN	BY	DATE	APP.	APP.				DWG. No.			SIZE	SHEET	REV.
REVISION RECORD					T.Harada							20535	A3	1/5

ITEMS	SPECIFICATION
RATING VOLTAGE	200V AC/DC (PER CONTACT PIN)
RATING AMPERAGE (FOR CONTACT)	0.3A AC/DC (PER CONTACT PIN) IN CASE OF APPLYING 0.5A PER CONTACT PIN, THE TOTAL CURRENT OF THE WHOLE CONNECTOR SHALL BE 15.0A OR LOWER.
OPERATING TEMPERATURE	233~358K(−40°C~+85°C)
OPERATING HUMIDITY	85% MAX.(NON-CONDENSING)
CONTACT RESISTANCE (FOR SIGNAL CONTACT)	INITIAL : 60mohm MAX. / AFTER TEST : $\triangle$ 40mohm MAX.
INSULATION RESISTANCE	INITIAL : 100Mohm MIN. / AFTER TEST : 100Mohm MIN.
DIELECTRIC WITHSTANDING VOLTAGE	AC250V 1min
DURABILITY	30 CYCLES
MATING FORCE (INITIAL / AFTER TEST)	10P : 6.0N MAX. 15P : 9.0N MAX. 20P : 12.0N MAX. 24P : 14.4N MAX. 30P : 18.0N MAX. 40P : 24.0N MAX.
UNMATING FORCE (INITIAL / AFTER TEST)	10P : 1.0N MIN. 15P : 1.5N MIN. 20P : 2.0N MIN. 24P : 2.4N MIN. 30P : 3.0N MIN. 40P : 4.0N MIN.
COPLANARITY	0.10 MAX.
PRODUCT SPECIFICATION	PRS-1670
TEST REPORT	TR-12108 (P/N: 20535-0**E-02) TR-25063 (P/N: 20535-0**E-02-P)
PACKING STANDARD	300-997
INSTRUCTION MANUAL	HIM-12003
APPEARANCE CRITERIA No.	QLS-A***

ANGLE	±2°	6 OVER 30 MAX.	±0.3	PROJECTION	SERIES No.	CUSTOMER COPY		
6 MAX.	±0.2	30 OVER 120 MAX.	±0.5		R6			
GENERAL TOLERANCE.				TITLE EVAFLEX® 5-VS		SCALE		
DWG.	DATE					UNIT		
CHK.						mm		
APP.						DWG. No.	20535	SIZE
						A3	2/5	15

PART No.	POS.	B	G	H
20535-010E-02-*	10P	4.50	7.04	5.80
20535-015E-02-*	15P	7.00	9.54	8.30
20535-020E-02-*	20P	9.50	12.04	10.80
20535-024E-02-*	24P	11.50	14.04	12.80
20535-030E-02-*	30P	14.50	17.04	15.80
20535-040E-02-*	40P	19.50	22.04	20.80

RECOMMENDED FFC DIMENSION



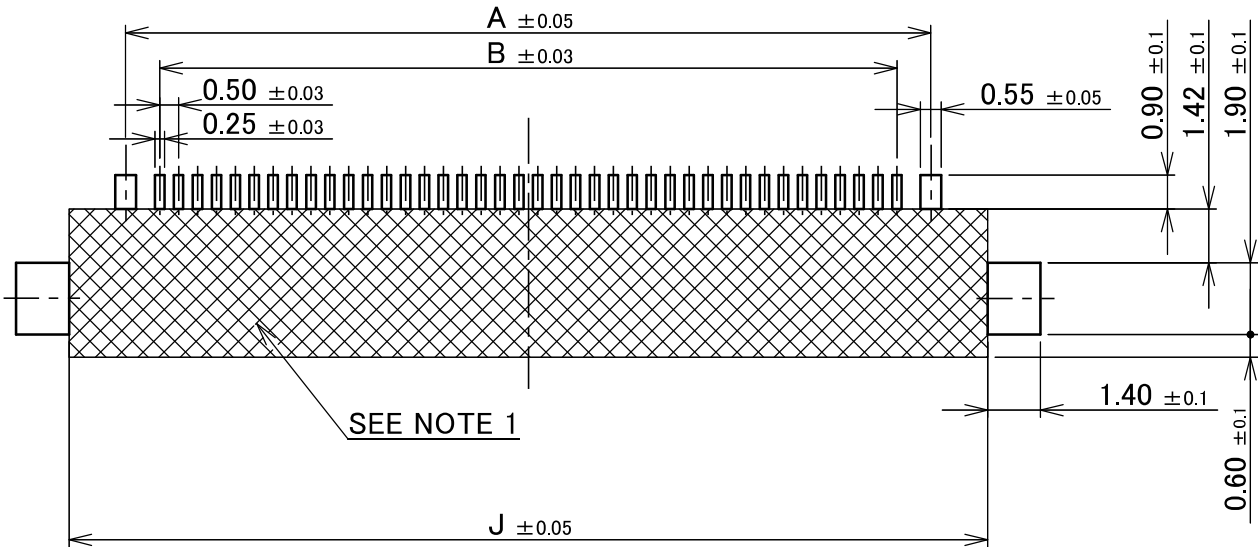
- NOTES
- 1.DIFFERENTIAL IMPEDAMCE : 100Ω
 - 2.MANUFACTURE CASE① or CASE②
 - 3. SELECT A MATERIAL WITH A SOFTENING TEMPERATURE OF 85°C OR HIGHER FOR THE PATTERN ADHESIVE PART OF FFC.

9	SHIELD TAPE	METALIC FILM	-
8	INTERLAYER	ARBITRARY	-
7	GROUND PLATE	METARIC FILM	POLISH or HALF POLISH Sn PLATING
6	REINFORCED TAPE	ARBITRARY	-
5	INSULATION FILM	ARBITRARY	-
4	CONDUCTOR	COPPER ALLOY	CONTACT AREA: Au 0.05 μ m MIN. OVER Ni 0.5 μ m MIN.
NO.	DISCRIPTION	MATERIAL	FINISH , REMARKS

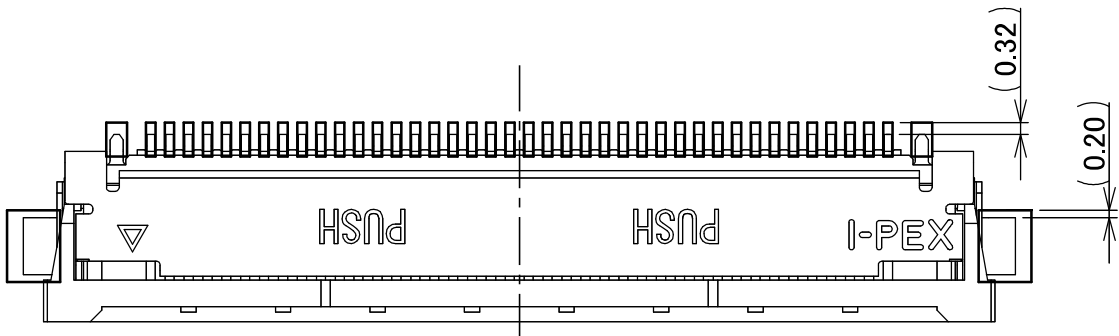
ANGLE	±2°	6 OVER 30 MAX.	±0.3	PROJECTION 	SERIES No. R6	CUSTOMER COPY		
6 MAX.	±0.2	30 OVER 120 MAX.	±0.5					
GENERAL TOLERANCE.				TITLE EVAFLEX® 5-VS		SCALE	I-PEX	
DWG.	DATE					5:1		
CHK.						UNIT		
						mm		
APP.				DWG. No. 20535		SIZE A3	SHEET 3/5	REV. 15

Recommended P/N		20535-0**E-02-P		
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PART No.	POS.	A	B	J
20535-010E-02-*	10P	6.30	4.50	9.30
20535-015E-02-*	15P	8.80	7.00	11.80
20535-020E-02-*	20P	11.30	9.50	14.30
20535-024E-02-*	24P	13.30	11.50	16.30
20535-030E-02-*	30P	16.30	14.50	19.30
20535-040E-02-*	40P	21.30	19.50	24.30

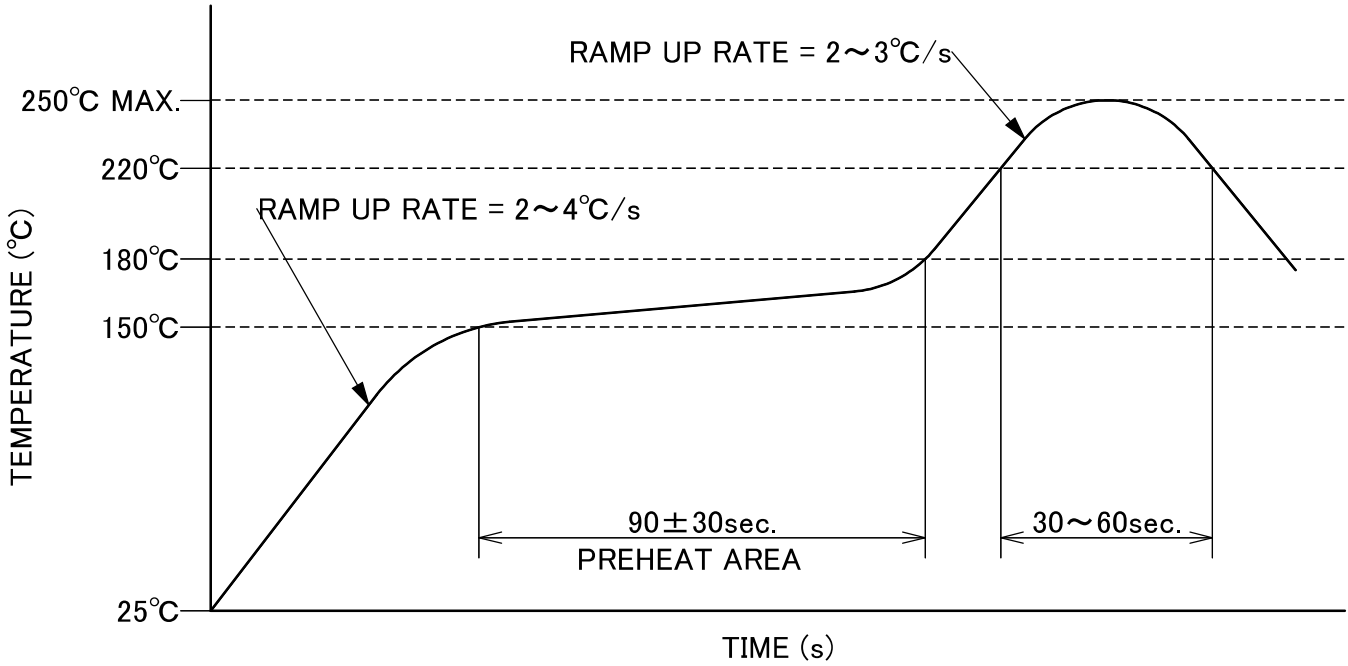


RECOMMENDED PCB & METALMASK LAYOUT
METALMASK THICKNESS: t=0.12



CONNECTOR ON RECOMMENDED FOOTPRINT PATTERN

NOTE
1. SOLDER RESIST MUST BE APPLIED TO THIS AREA.



REFLOW TEMPERATURE PROFILE
SENJU METAL INDUSTRY CO., LTD. : M705-SHF(Sn96.5 Ag3.0 Cu0.5)

ANGLE	±2°	6 OVER 30 MAX.	±0.3	PROJECTION 	SERIES No. R6	CUSTOMER COPY		
6 MAX.	±0.2	30 OVER 120 MAX.	±0.5					
GENERAL TOLERANCE.				TITLE EVAFLEX® 5-VS		SCALE	I-PEX	
DWG.	DATE					5:1		
CHK.						UNIT		
			mm					
APP.				DWG. No.	20535	SIZE	SHEET	REV.
						A3	4/5	15

